



Material Content Data Sheet



Sales Product Name		BSG0811ND		Issued		27. September 2017		
MA#		MA001288508						
Package		PG-TISON-8-4		Weight*		112.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.270	1.13	1.13	11269	11269
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	zinc	7440-66-6	0.043	0.04		382	
	non noble metal	iron	7439-89-6	0.862	0.76		7643	
wire	non noble metal	copper	7440-50-8	34.984	31.03	31.84	310322	318443
	non noble metal	copper	7440-50-8	0.010	0.01	0.01	85	85
	encapsulation	organic material	carbon black	1333-86-4	0.093	0.08		827
plating	plastics	epoxy resin	-	4.800	4.26		42576	
	inorganic material	silicondioxide	60676-86-0	41.708	36.98	41.32	369960	413363
	leadfinish	non noble metal	tin	7440-31-5	1.180	1.05	1.05	10465
solder	noble metal	silver	7440-22-4	0.087	0.08	0.08	768	768
heat sink CLIP	non noble metal	silver	7440-22-4	0.048	0.04		423	
	non noble metal	tin	7440-31-5	0.038	0.03		338	
	non noble metal	lead	7439-92-1	1.822	1.62	1.69	16163	16924
*deviation	inorganic material	phosphorus	7723-14-0	0.008	0.01		69	
	non noble metal	zinc	7440-66-6	0.031	0.03		274	
	non noble metal	iron	7439-89-6	0.619	0.55		5488	
	non noble metal	copper	7440-50-8	25.123	22.29	22.88	222852	228683
Sum in total:						100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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